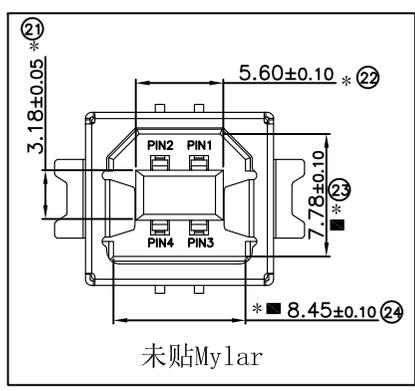
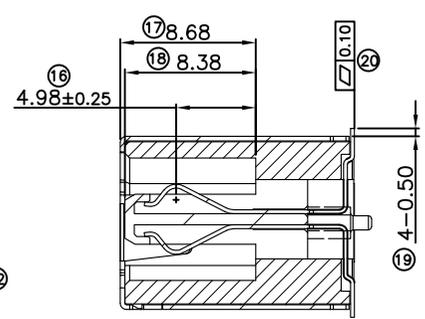
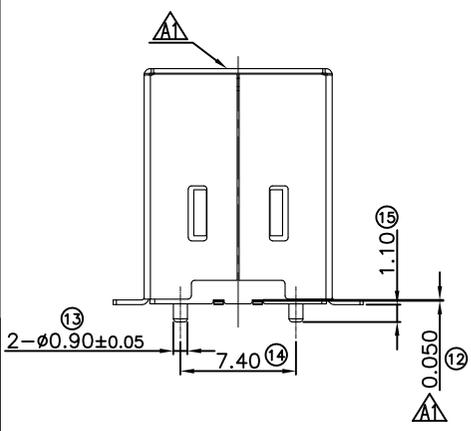
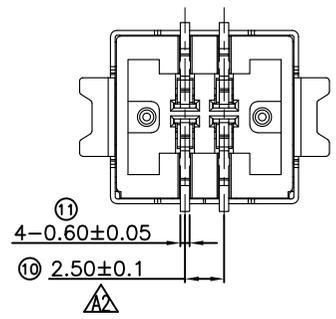
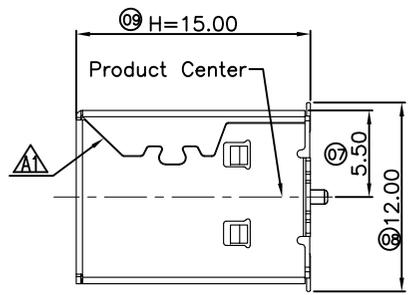
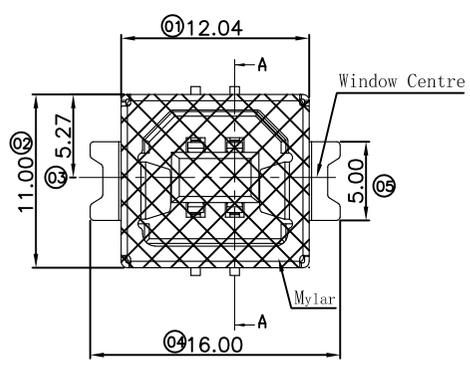
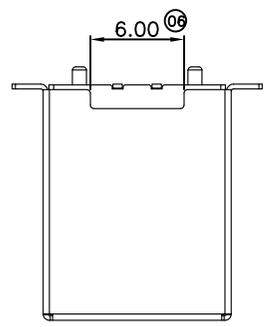
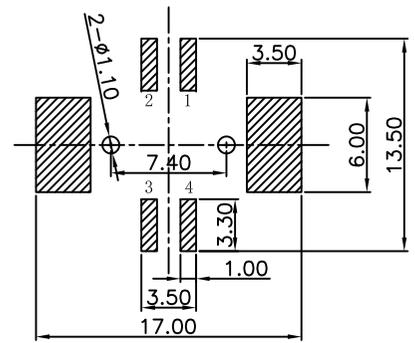


GP Component

REV.	ECN NO.	LOCATIONS	DESCRIPTION	DATE	DESIGN
A0			Initial	2017/12/14	Phebe Su
A1			Change REV.	2022/01/10	Ken Lin
A2	ECN20240403001		Change DIM.	2024/04/03	Ken Lin

NOTE:

- Material:
 - Housing: LCP, Black(Halogen free); Thermoplastics, UL94V-0;
 - Contact: Copper Alloy
 - Shell: Copper Alloy
- Finish:
 - Contact: Gold Flash Plated on Contact Area, 80u" Tin Bright Plated on Solder Tails, 50u" Min.Nickel Underplating Over All.
 - Shell: 50u" Min.Nickel Underplating Over All.
- Specification:
 - 3.1: Voltage Current Rating: 1.5Amp. 30V/AC
 - 3.2: Electrical:
 - Insulation Resistance: 1000MΩ Min.
 - Contact Resistance: 20mΩ Max.
 - Dielectric Withstanding Voltage: 750V/AC 1Minute
 - 3.3: MECHANICAL
 - Mating force: 35N Max.
 - Unmating force: 10N Min.
 - Durability: 1500 cycles Min.



MATRIX PART NO:
MUSB 04 - 01 - 334

MATRIX USB — Pin Number — Plating
01:Gold Flash
15:15u"
30:30u"

PIN NO.	PIN 1	PIN 2	PIN 3	PIN 4
SLGNL NAME	V BUS	D-	D+	GND
REMARK	USB 2.0 CONTACT PINS			

		Matrix Electronics Co.,Ltd			
		TOLERANCE: X:X ±0.30 X:XX ±0.20 X:XXX ±0.15 ANGLE: ±3°		DESIGN BY : Ken Lin	
		DATE : 2024/04/03		PART NAME: USB 2.0 BF Vertical SMD	
UNIT: mm [inch]		CHECKED BY: Vicky Hsieh		DATE : 2024/04/03	
SCALE:1:1 SIZE:A4		APPROVED BY1: Richard Hsieh		PART NO. MUSB04-01-334	
		APPROVED BY2: Richard Hsieh		DATE : 2024/04/03	
				MOLD NO. NA	
				DRAW NO.	
				SHEET NO. 1 OF 1	